

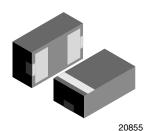
ESD-Protection Diode in LLP1006-2L

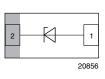
Features

- Ultra compact LLP1006-2L package
- Low package height < 0.4 mm
- 1-line ESD-protection
- Low leakage current < 0.2 μA
- Low load capacitance C_D = 38 pF (V_R = 2.5 V; f = 1 MHz)
- ESD-protection acc. IEC 61000-4-2
 - ± 30 kV contact discharge
 - ± 30 kV air discharge
- High surge current acc. IEC61000-4-5 I_{PP} > 8 A
- Soldering can be checked by standard vision inspection. No X-ray necessary
- · Lead (Pb)-free component
- · Pin plating NiPdAu (e4) no whisker growth
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



GREEN (5-2008)*





Marking (example only)



Bar = Cathode marking

X = Date code

Y = Type code (see table below)

Ordering Information

Device name Ordering code		Taped units per reel (8 mm tape on 7" reel)	Minimum order quantity		
VESD05A1C-HD1	VESD05A1C-HD1-GS08	8000	8000		

Package Data

Device name	Package name	Type code	Weight	Molding compound flammability rating	Moisture sensitivity level	Soldering conditions
VESD05A1C-HD1	LLP1006-2L	F	0.72 mg	UL 94 V-0	MSL level 1 (according J-STD-020)	260 °C/10 s at terminals

Absolute Maximum Ratings

Rating	Test conditions	Symbol	Value	Unit
Peak pulse current	Acc. IEC 61000-4-5, $t_P = 8/20 \mu s/single shot$	I _{PPM}	8	Α
Peak pulse power	Acc. IEC 61000-4-5, t _P = 8/20 μs/single shot	P _{PP}	80	W
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
	Air discharge acc. IEC 61000-4-2; 10 pulses	V_{ESD}	± 30	kV
Operating temperature	Junction temperature T _J		- 40 to + 125	°C
Storage temperature		T _{STG}	- 55 to + 150	°C

^{*} Please see document "Vishay Green and Halogen-Free Definitions (5-2008)" http://www.vishay.com/doc?99902

Document Number 81798 Rev. 1.2, 02-Sep-08



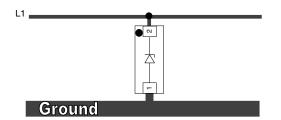
BiAs-Mode (Bidirectional Asymmetrical protection mode)

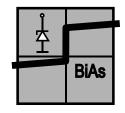
With the **VESD05A1C-HD1** one signal- or data-lines (L1) can be protected against voltage transients. With pin 1 connected to ground and pin 2 connected to a signal- or data-line which has to be protected. As long as the voltage level on the data- or signal-line is between 0 V (ground level) and the specified **Maximum Reverse Working Voltage** (**V**_{RWM}) the protection diode between data line and ground offers a high isolation to the ground line. The protection device behaves like an open switch.

As soon as any positive transient voltage signal exceeds the break through voltage level of the protection diode, the diode becomes conductive and shorts the transient current to ground. Now the protection device behaves like a closed switch. The Clamping Voltage (V_C) is defined by the BReakthrough Voltage (V_{BR}) level plus the voltage drop at the series impedance (resistance and inductance) of the protection device.

Any negative transient signal will be clamped accordingly. The negative transient current is flowing in the forward direction of the protection diode. The low Forward Voltage (V_F) clamps the negative transient close to the ground level.

Due to the different clamping levels in forward and reverse direction the **VESD05A1C-HD1** clamping behaviour is <u>Bi</u>directional and <u>Asymmetrical</u> (**BiAs**).





20925

Electrical Characteristics

Ratings at 25 °C, ambient temperature, unless otherwise specified

VESD05A1C-HD1

BiAs mode (between pin 1 and pin 2)

Parameter	Test conditions/remarks	Symbol	Min.	Тур.	Max.	Unit
Protection paths	Number of lines which can be protected	N _{lines}			1	lines
Reverse stand off voltage	at I _R = 1 μA	V _{RWM}	5			V
Reverse current	at V _R = 5 V	I _R		0.03	0.2	μΑ
Reverse break down voltage	at I _R = 1 mA	V _{BR}	6	6.7	8	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		7.1	8	V
	at $I_{PP} = I_{PPM} = 8 A$	V _C		9.3	10	V
Forward clamping voltage	at I _{PP} = 0.2 A	V _F		0.95	1.2	V
	at I _{PP} = 1 A	V _F		1.1	1.5	V
	at I _{PP} = I _{PPM} = 8 A	V _F		1.9		V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C _D		63	75	pF
	at V _R = 2.5 V; f = 1 MHz	C _D		38		pF





Typical Characteristics

T_{amb} = 25 °C, unless otherwise specified

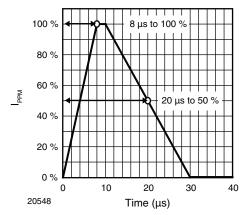


Figure 1. 8/20 µs Peak Pulse Current Wave Form (acc. IEC 61000-4-5)

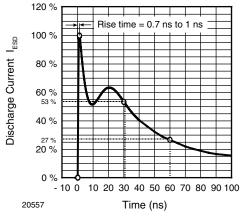


Figure 2. ESD Discharge Current Wave Form acc. IEC 61000-4-2 (330 $\Omega/150$ pF)

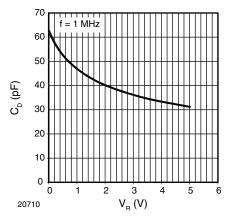


Figure 3. Typical Capacitance C_D vs. Reverse Voltage V_R

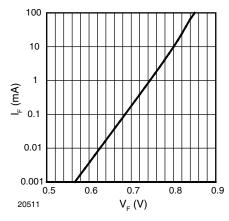


Figure 4. Typical Forward Current $\rm I_F$ vs. Forward Voltage $\rm V_F$

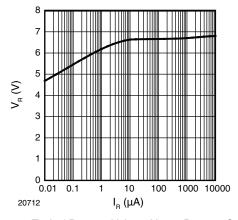


Figure 5. Typical Reverse Voltage V_R vs. Reverse Current I_R

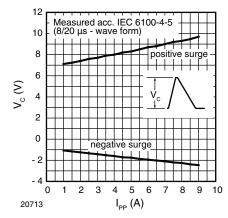


Figure 6. Typical Peak Clamping Voltage vs. Peak Pulse Current I_{PP}



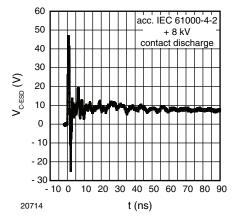


Figure 7. Typical Clamping Performance at + 8 kV Contact Discharge (acc. IEC 61000-4-2)

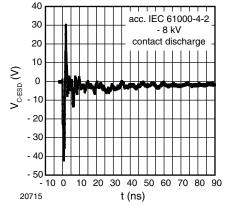


Figure 8. Typical Clamping Performance at - 8 kV Contact Discharge (acc. IEC 61000-4-2)

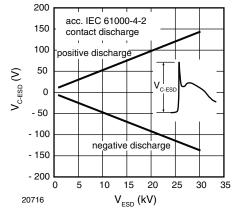
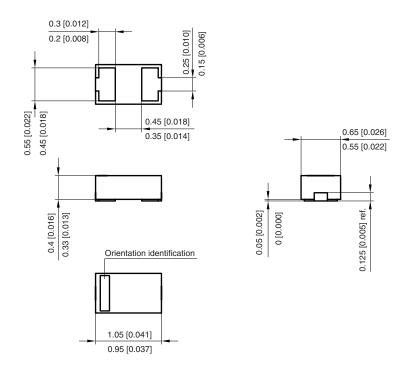
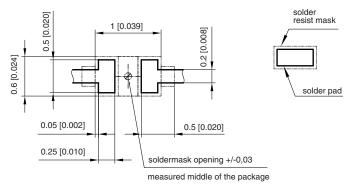


Figure 9. Typical Peak Clamping Voltage at ESD Contact Discharge (acc. IEC 61000-4-2)

Package Dimensions in millimeters (inches): LLP1006-2L



foot print recommendation:



Document no.:S8-V-3906.04-005 (4) Created - Date: 13.July.2007 Rev. 4 - Date: 28.Aug.2008 20812

VESD05A1C-HD1

Vishay Semiconductors



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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Document Number 81798

Rev. 1.2, 02-Sep-08



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Revision: 18-Jul-08

Document Number: 91000 www.vishay.com